ABSTRACT OF THE DISCLOSURE

LEAD FRAME AND METHOD OF MANUFACTURING THE SAME AND SEMICONDUCTOR DEVICE

In the lead frame of the present invention, a common wiring portion (ground ring) is arranged around a die pad at a predetermined interval to be connected partially to the die pad, projection portions projected toward the die pad side are provided to side portions of the common wiring portion, a plurality of leads are provided away from the common wiring portion to extend outward from a periphery of the common wiring portion, and the projection portions of the common wiring portion are pressed partially by the die upon cutting off the leads from the common wiring portion by a die.

[Fig. 5]